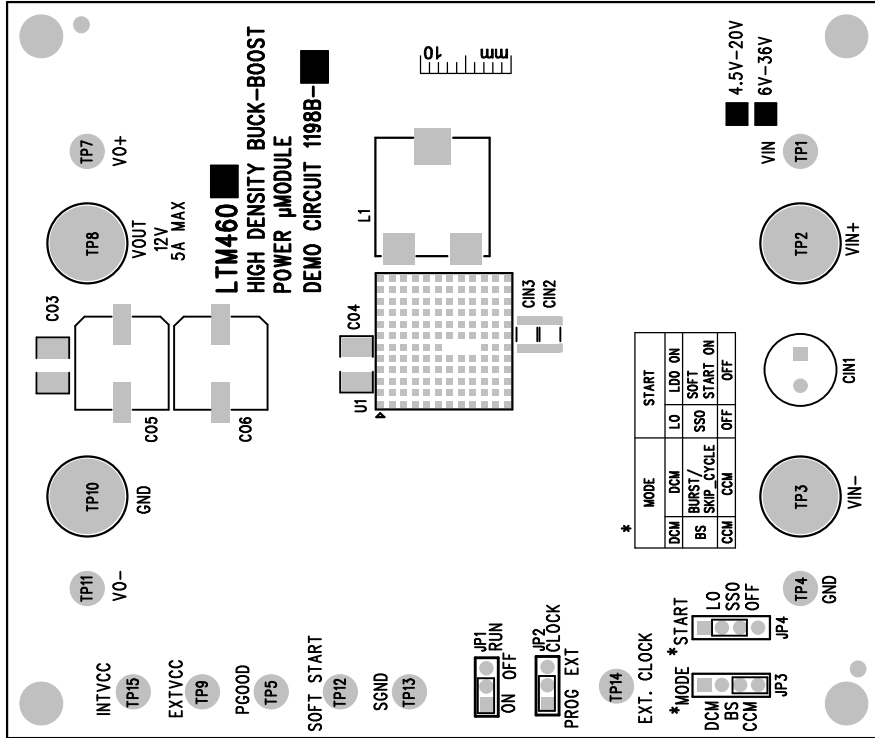
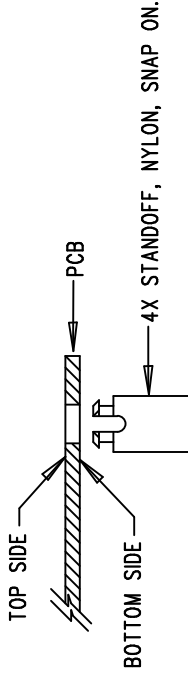


REVISION HISTORY			
ECO	REV	DESCRIPTION	APP. ENG.
1	1	PRODUCTION	SAM Y.
			DATE
			9-28-12

NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS AS SHOWN ON ASSY DRAWING.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
7. INSTALL 4 STANDOFFS AT 4 LOCATIONS AS SHOWN BELOW:



APPROVALS		LINEAR TECHNOLOGY		1630 MCCARTHY BLVD MILPITAS, CA 95035 PH: (408)432-1900 WWW.LINEAR.COM LTC CONFIDENTIAL - FOR CUSTOMER USE ONLY	
PCB DES.	HZ	TITLE: TOP ASSEMBLY DRAWING		HIGH DENSITY BUCK-BOOST POWER μMODULE®	
APP ENG.	SAM Y.	SIZE		IC NO. LTM4605EV/LTM4607EV	
		N/A		REV. 1	
SCALE = NONE		FILENAME: DC1198B-1.PCB		SHT 1 OF 2	